

ABSTRACT

In some embodiments, a package suitable to contain one or more semiconductor dies includes one or more solder-balls at an underside of said package and one or more external leads at a side edge of said package. Any or all of the solder-balls and external leads may serve as external electrical terminations of the package. The external leads may be surface mount leads and/or through-hole leads. In some embodiments, a printed circuit board may include pads designed to be soldered to solder-balls of a package and pads designed to be soldered to external leads of the package.